

BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu\,\text{PC1060}$

2.5 V HIGH PRECISION REFERENCE VOLTAGE CIRCUIT

DESCRIPTION

The μ PC1060 are high accuracy and low drift voltage references of 2.5 V output voltage.

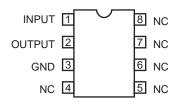
This IC can operate under wide range input voltage, and applied for 8 to 12 bits D/A converters.

★ FEATURES

High Accuracy	$Vo = 2.5 V \pm 1 \%$
• Low Temperature Coefficient	$\Delta \text{Vo}/\Delta \text{T} \le 40 \text{ ppm/}^{\circ}\text{C}$
Low Supply Current	Icc ≤ 1.5 mA
Wide Supply Voltage Range	$4.5~\text{V} \leq \text{V}_{\text{IN}} \leq 40~\text{V}$
Low Load Regulation	REG∟ ≤ 10 mV

PIN CONFIGURATION

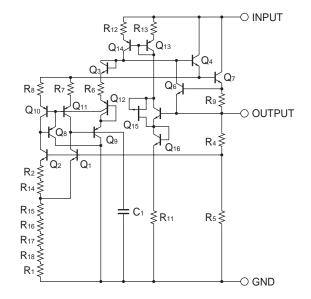
8-pin plastic DIP (7.62 mm (300)) $\mu\,\mathrm{PC}1060\mathrm{C}$



★ ORDERING INFORMATION

Part Number	Package
μ PC1060C	8-pin plastic DIP (7.62 mm (300))

EQUIVALENT CIRCUIT



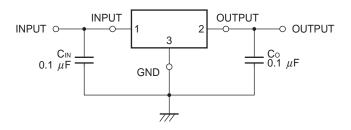
The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ABSOLUTE MAXIMUM RATINGS (TA = +25 °C, unless otherwise specified.)

Parameter	Symbol	Ratings	Unit
Input Voltage	VIN	−0.3 to +40	V
Total Power Dissipation	PT	350	mW
Operating Ambient Temperature	TA	−20 to +70	°C
Storage Temperature	T _{stg}	−55 to +125	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

TYPICAL CONNECTION



RECOMMENDED OPERATING CONDITIONS

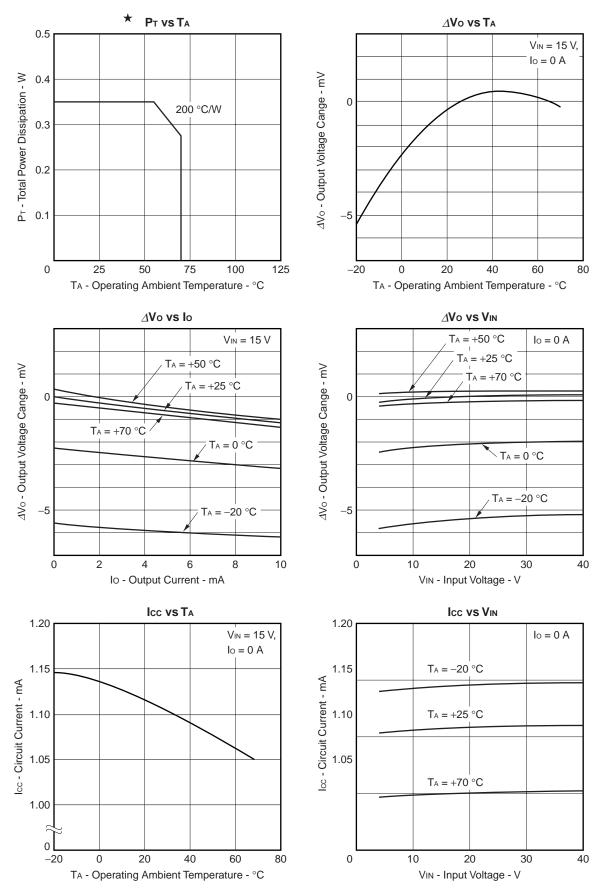
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Input Voltage	Vin	4.5		40	V
Output Current	lo	0		10	mA
Internal Power Dissipation	PD			270	mW
Operating Ambient Temperature	TA	-20		+70	°C

Caution The recommended operating range may be exceeded without causing any problems provided that the absolute maximum ratings are not exceeded. However, if the device is operated in a way that exceeds the recommended operating conditions, the margin between the actual conditions of use and the absolute maximum ratings is small, and therefore thorough evaluation is necessary. The recommended operating conditions do not imply that the device can be used with all values at their maximum values.

ELECTRICAL CHARACTERISTICS (VIN = 15 V, Io = 0 A, TA = +25 °C, unless otherwise specified.)

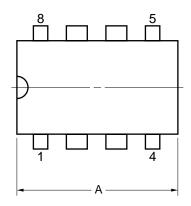
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Output Voltage	Vo		2.475	2.5	2.525	V
Output Voltage Change	ΔVo	0 °C ≤ TA ≤ 70 °C			7.0	mV
Temperature Coefficient of Output Voltage	ΔVο/ΔΤ	0 °C ≤ TA ≤ 70 °C			40	ppm/°C
Line Regulation	REGIN	15 V ≤ V _{IN} ≤ 40 V			4.5	mV
		4.5 V ≤ V _{IN} ≤ 15 V			3.0	mV
Load Regulation	REGL	0 A ≤ lo ≤ 10 mA			10	mV
Ripple Rejection	R•R	5 V ≤ V _{IN} ≤ 40 V, f = 120 Hz		90		dB
Output Noise Voltage	Vn	$4.5 \text{ V} \le \text{V}_{\text{IN}} \le 40 \text{ V}, 0 \text{ A} \le \text{Io} \le 10 \text{ mA},$ $P_{\text{T}} \le 350 \text{ mW}$		80		μ V _{p-p}
Short Circuit Current	lOshort	Vo = 0 V		17		mA
Circuit Current	Icc				1.5	mA

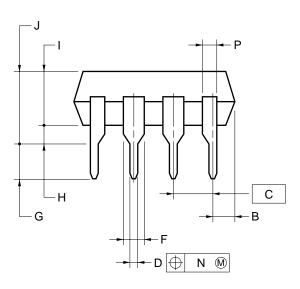
TYPICAL CHARACTERISTIC (TA = +25 °C, unless otherwise specified. Nominal)

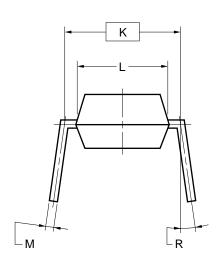


PACKAGE DRAWING

8-PIN PLASTIC DIP (7.62mm(300))







NOTES

- 1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
- 2. Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS
Α	10.16 MAX.
В	1.27 MAX.
С	2.54 (T.P.)
D	0.50±0.10
F	1.4 MIN.
G	3.2±0.3
Н	0.51 MIN.
T	4.31 MAX.
J	5.08 MAX.
K	7.62 (T.P.)
L	6.4
М	0.25+0.10
N	0.25
P	0.9 MIN.
R	0~15°

P8C-100-300B,C-2

* RECOMMENDED SOLDERING CONDITIONS

When soldering this product, it is highly recommended to observe the conditions as shown below.

If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document "Semiconductor Device Mounting Technology Manual" (C10535E).

Type of Through-hole Device

μ PC1060C : 8-pin plastic DIP (7.62 mm (300))

Process	Conditions		
Wave soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less.		

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

REFERENCE DOCUMENTS

Semiconductor Device Mounting Technology Manual C10535E Semiconductor Selection Guide -Products and Packages- X13769X **NEC** μ PC1060

[MEMO]

NEC μ PC1060

[MEMO]

- The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
- No part of this document may be copied or reproduced in any form or by any means without the prior written
 consent of NEC Corporation. NEC Corporation assumes no responsibility for any errors which may appear in
 this document.
- NEC Corporation does not assume any liability for infringement of patents, copyrights or other intellectual property
 rights of third parties by or arising from use of a device described herein or any other liability arising from use
 of such device. No license, either express, implied or otherwise, is granted under any patents, copyrights or other
 intellectual property rights of NEC Corporation or others.
- Descriptions of circuits, software, and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software, and information in the design of the customer's equipment shall be done under the full responsibility of the customer. NEC Corporation assumes no responsibility for any losses incurred by the customer or third parties arising from the use of these circuits, software, and information.
- While NEC Corporation has been making continuous effort to enhance the reliability of its semiconductor devices, the possibility of defects cannot be eliminated entirely. To minimize risks of damage or injury to persons or property arising from a defect in an NEC semiconductor device, customers must incorporate sufficient safety measures in its design, such as redundancy, fire-containment, and anti-failure features.
- NEC devices are classified into the following three quality grades:
 - "Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.
 - Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
 - Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
 - Specific: Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.